

Title (en)
SAFETY FUSE FOR A CHIP

Title (de)
SCHMELZSICHERUNG FÜR EINEN CHIP

Title (fr)
FUSIBLE POUR PUCE

Publication
EP 1766648 A1 20070328 (DE)

Application
EP 05776175 A 20050627

Priority
• EP 2005006894 W 20050627
• DE 102004033251 A 20040708

Abstract (en)
[origin: US10354826B2] To produce a cost-effective fuse in chip design, which is applied to a carrier substrate made of a Al₂O₃ ceramic having a high thermal conductivity, and which is provided with a fusible metallic conductor and a cover layer, in which the melting point of the metallic conductor may be defined reliably, it is suggested that an intermediate layer having low thermal conductivity be positioned between the carrier substrate and the metallic conductor, the intermediate layer being formed by a low-melting-point inorganic glass paste applied in the screen-printing method or an organic intermediate layer applied in island printing. Furthermore, a method for manufacturing the fuse is specified.

IPC 8 full level
H01H 85/00 (2006.01); **H01H 69/02** (2006.01); **H01H 85/046** (2006.01)

CPC (source: EP KR US)
H01H 69/022 (2013.01 - EP US); **H01H 85/006** (2013.01 - EP US); **H01H 85/0411** (2013.01 - EP US); **H01H 85/046** (2013.01 - EP KR US); **H01H 2085/0414** (2013.01 - EP US); **Y10T 29/49107** (2015.01 - EP US)

Designated contracting state (EPC)
AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IS IT LI LT LU MC NL PL PT RO SE SI SK TR

DOCDB simple family (publication)
WO 2006005435 A1 20060119; AT E462194 T1 20100415; CN 101010768 A 20070801; CN 101010768 B 20110330; DE 102004033251 B3 20060309; DE 502005009279 D1 20100506; EP 1766648 A1 20070328; EP 1766648 B1 20100324; JP 2008505466 A 20080221; KR 101128250 B1 20120323; KR 20070038143 A 20070409; TW 200612453 A 20060416; TW I413146 B 20131021; US 10354826 B2 20190716; US 2008303626 A1 20081211; US 2016372293 A1 20161222; US 9368308 B2 20160614

DOCDB simple family (application)
EP 2005006894 W 20050627; AT 05776175 T 20050627; CN 200580029173 A 20050627; DE 102004033251 A 20040708; DE 502005009279 T 20050627; EP 05776175 A 20050627; JP 2007519668 A 20050627; KR 20077002904 A 20050627; TW 94122828 A 20050706; US 201615180586 A 20160613; US 57178705 A 20050627